


FLEX

 **MEMS &
SENSORS®**
Technical Congress

February 18–21, 2019 | Hyatt Regency | Monterey, California



2019 Exhibitor Prospectus

FLEX 2019 and MEMS & Sensors Technical Congress share the exhibition floor to provide a central location for participants to connect, collaborate and innovate. Networking events and breaks are held on the show floor to bring a dynamic and highly interactive element to both conferences.

RESERVE YOUR BOOTH TODAY

Organized by:



Focused on the creation and integration of flexible hybrid and printed electronics from R&D to manufacturing.

Building Outside the Box

FLEX 2019 brings together professionals in the flexible, hybrid, and printed electronics field. They come to find customers, suppliers, and partners, and to learn about the latest technology developments.

Short-courses, social events, keynotes, poster sessions, FLEXI Awards, Future Innovators Award, and TechTALKS—plus over 100 technical and marketing presentations—are the many features of the FLEX 2019 conference.

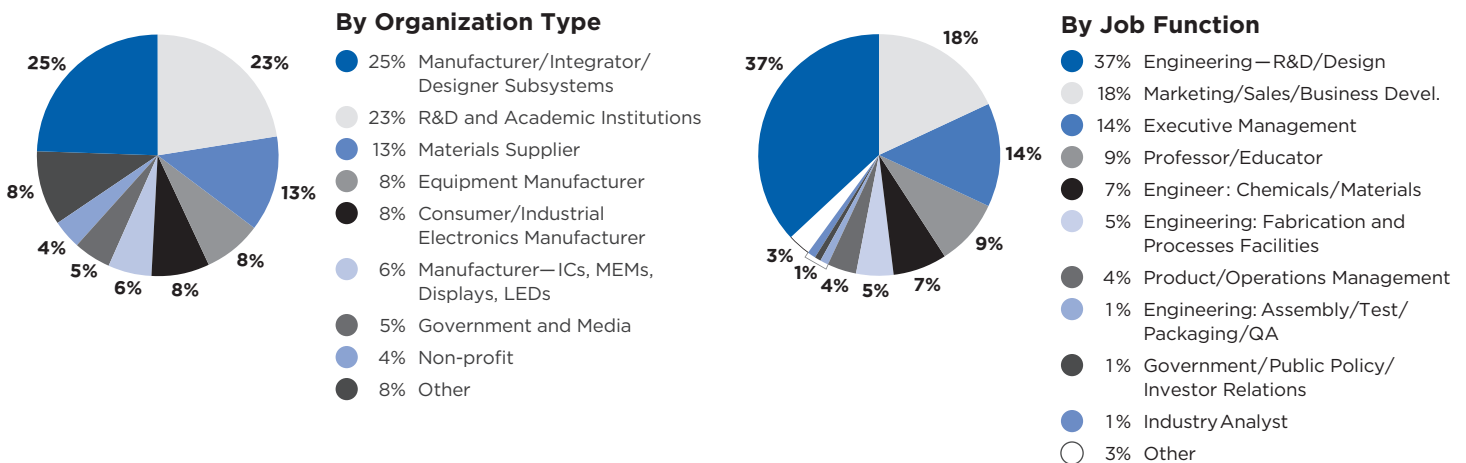
FLEX 2019 Topics

- End-market Requirements and Case Studies
- Flexible Electrical Components
- IoT
- Materials
- Processing and Manufacturing
- Smart Manufacturing
- Smart MedTech
- Smart Transportation
- Standards
- Strategy and Business

Event Attendee Profile

An estimated 95% of attendees have technical backgrounds and are eager to see and learn about the latest offerings in the flexible, hybrid, printed, and MEMS and sensors industry.

FLEX 2018 ATTENDEES More than 600 attendees represent 400+ companies, universities, and other organizations.





Focused on the market opportunities and technology challenges for MEMS and sensors manufacturers and suppliers.

Sensor Systems Enabling Autonomous Mobility

The MEMS & Sensors Technical Congress (MSTC) brings together professionals to collaborate on finding solutions to industry-wide challenges. Speakers will present system-level solutions incorporating MEMS and/or sensor devices, applications, and innovative technologies.

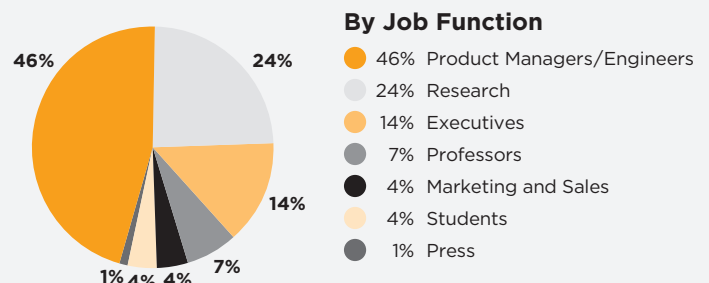
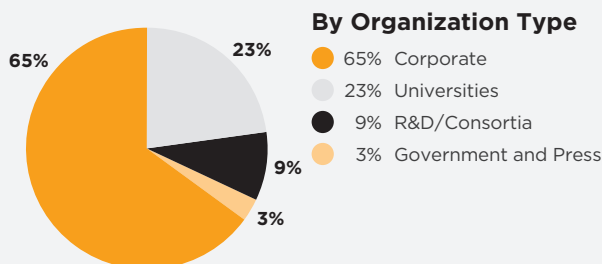
MSTC 2019 Topics

- 5G and Autonomous Mobility
- AI, Machine Learning, and Sensing for Autonomous Mobility
- Autonomy in Private and Public Transportation for Land, Sea, and Air
- Emerging Technologies, R&D and Investment Trends in Autonomous Mobility
- Flexible, Hybrid and Printed Sensor Solutions for Autonomous Mobility
- Environmental Sensing
- MEMS-based Displays and Projectors for Mobile/Remote Applications
- Mobile and Remote Monitoring IoT Applications
- New Sensor-based Hardware Additions to Mobile Phones and Tablets
- Sensors in Food and Agriculture
- System Level Integration Challenges
- Wearable Devices for Sport, Fitness, and Medical Uses

Event Attendee Profile

MSTC attracts technical representatives from over 100 companies, universities, and R&D labs to engage in formal and informal information exchange, networking, and business collaboration.

MSTC 2018 ATTENDEES More than 125 attendees representing 65+ companies, universities, and other organizations.



FLEX and MSTC 2019 Booth Fees

Booths are sold in 80–100 square-foot increments, unless specified. Prices are calculated per square foot. (Use per square foot when calculating a single block of space — use per square feet when calculating multiple areas of space).

Pipe and Drape Standard Price

Member*
USD \$37.00

Non-member
USD \$49.50

* To receive member pricing, your SEMI Membership must be active and paid in full through the exposition.

2018 Exhibitors

- AIMCAL (Association of International Metallizers, Coaters and Laminators)
- Applied Materials
- Buhler
- Carestream Contract Manufacturing
- Carpe Diem Technologies
- CERADROP MGI
- Chemcut
- CONNECTEC JAPAN
- Corning
- Dark Field Technologies
- Delphon Industries
- Disco Hi-Tec America
- DuPont Teijin Films
- E Ink
- EAG Laboratories
- EMD Performance Materials
- ENrG, Inc.
- Fraunhofer FEP
- Georgia Institute of Technology
- GrollTex
- Harper Corporation of America
- Hionix
- IDTechEx
- Interlink Electronics
- J.A. Woollam
- Liquid X Printed Metals
- Materion
- Meyer Burger Technology
- MicroChem
- MicroConnex
- Nanotronics Imaging
- MOCON
- Namics Technologies
- New Way Air Bearings
- NextFlex
- NovaCentrix
- Optomec
- Oxford Instruments
- Plasma-Therm
- Printed Electronics Now/ Ink World
- Quantum Analytics
- Semilab
- Sentec E&E
- SERIA
- Sun Chemical
- Tango Systems
- TSI Semiconductors
- ULVAC Technologies
- Unisem
- Universal Instruments
- University of Washington—WA Clean Energy Testbeds
- Yasui Seiki-MIRWEC
- YUASA SYSTEM

Exhibit Dates:

Tuesday, February 19, 2019

Wednesday, February 20, 2019

Exhibitors Receive:

- Turn-key Exhibit Packages
- Conference Passes
- Meals and Receptions
- Priority Selection for TechTALK
- Event Guide and Web Listing
- Networking Receptions

Think Outside the Booth—

Become a FLEX and MSTC 2019 Sponsor

FLEX and MSTC offer innovative sponsorship opportunities for every sales and marketing objective.

Contact Us

Eric Rude

T: 1.408.943.7047

E: erude@semi.org

flex.semi.org

Organized by: